

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Forward Voltage @ $I_F = 10\text{mA}$	V_F	0.9	V

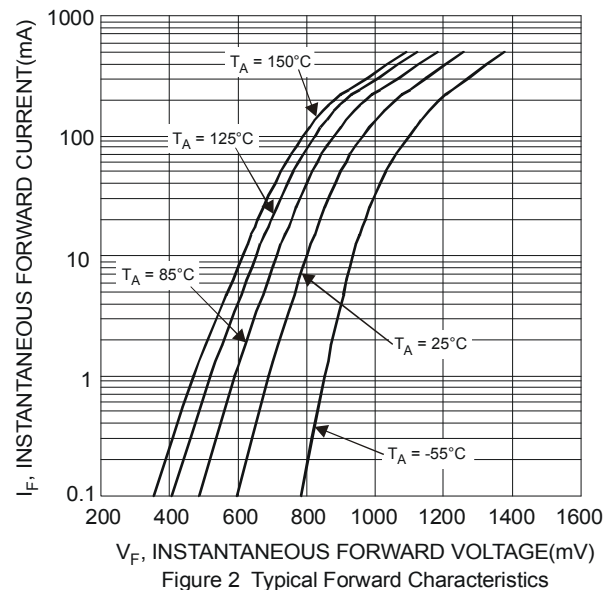
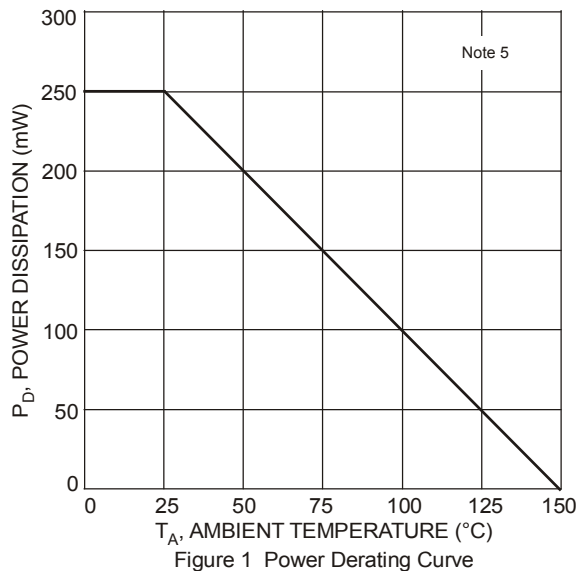
Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5) $T_A = +25^\circ\text{C}$	P_D	250	mW
Thermal Resistance, Junction to Ambient Air (Note 5) $T_A = +25^\circ\text{C}$	$R_{\theta JA}$	500	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	$^\circ\text{C}$

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Type Number	Marking Code	Zener Voltage Range (Note 6)				Maximum Zener Impedance f = 1kHz			Maximum Reverse Current (Note 6)		Temperature Coefficient @ I _{ZTC} mV/°C		Test Current I _{ZTC}	Maximum Capacitance (Note 7)
		V _Z @ I _{ZT}			I _{ZT}	Z _{ZT} @ I _{ZT}	Z _{ZK} @ I _{ZK}	I _{ZK}	I _R	@ V _R				C _T
		Nom (V)	Min (V)	Max (V)	mA	Ω		mA	μA	V	Min	Max	mA	pF
BZT52B15LP	6L	15	14.70	15.30	5	15	200	1	0.05	10.5	9.2	13.0	5	100

Notes: 5. Device mounted on FR-4 PCB with minimum recommended pad layout which can be found on our website at <http://www.diodes.com>.
 6. Short duration pulse test used to minimize self-heating effect.
 7. $f = 1\text{MHz}$, $V_R = 0\text{V}$, $T_A = +25^\circ\text{C}$.



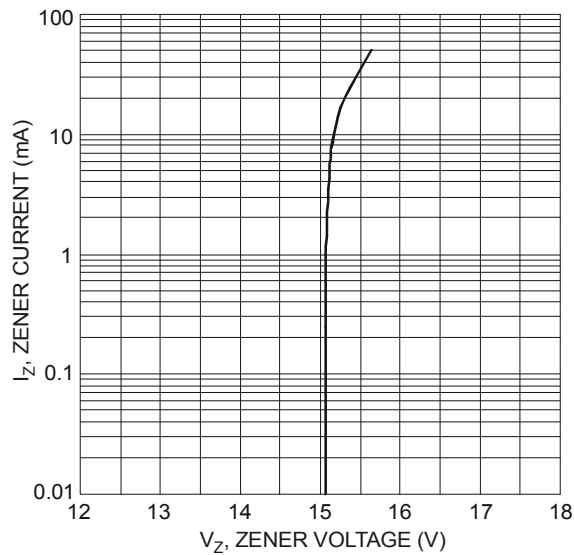
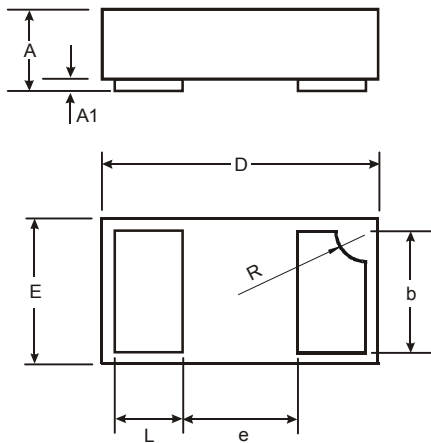


Figure 3 Typical Zener Breakdown Characteristics

Package Outline Dimensions

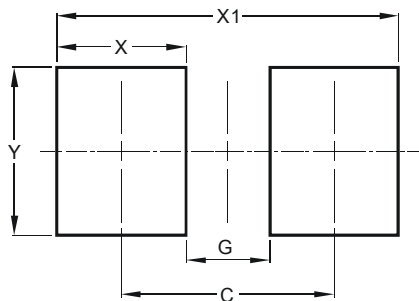
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



X1-DFN1006-2			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0	0.05	0.03
b	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.40
L	0.20	0.30	0.25
R	0.05	0.15	0.10
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70

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